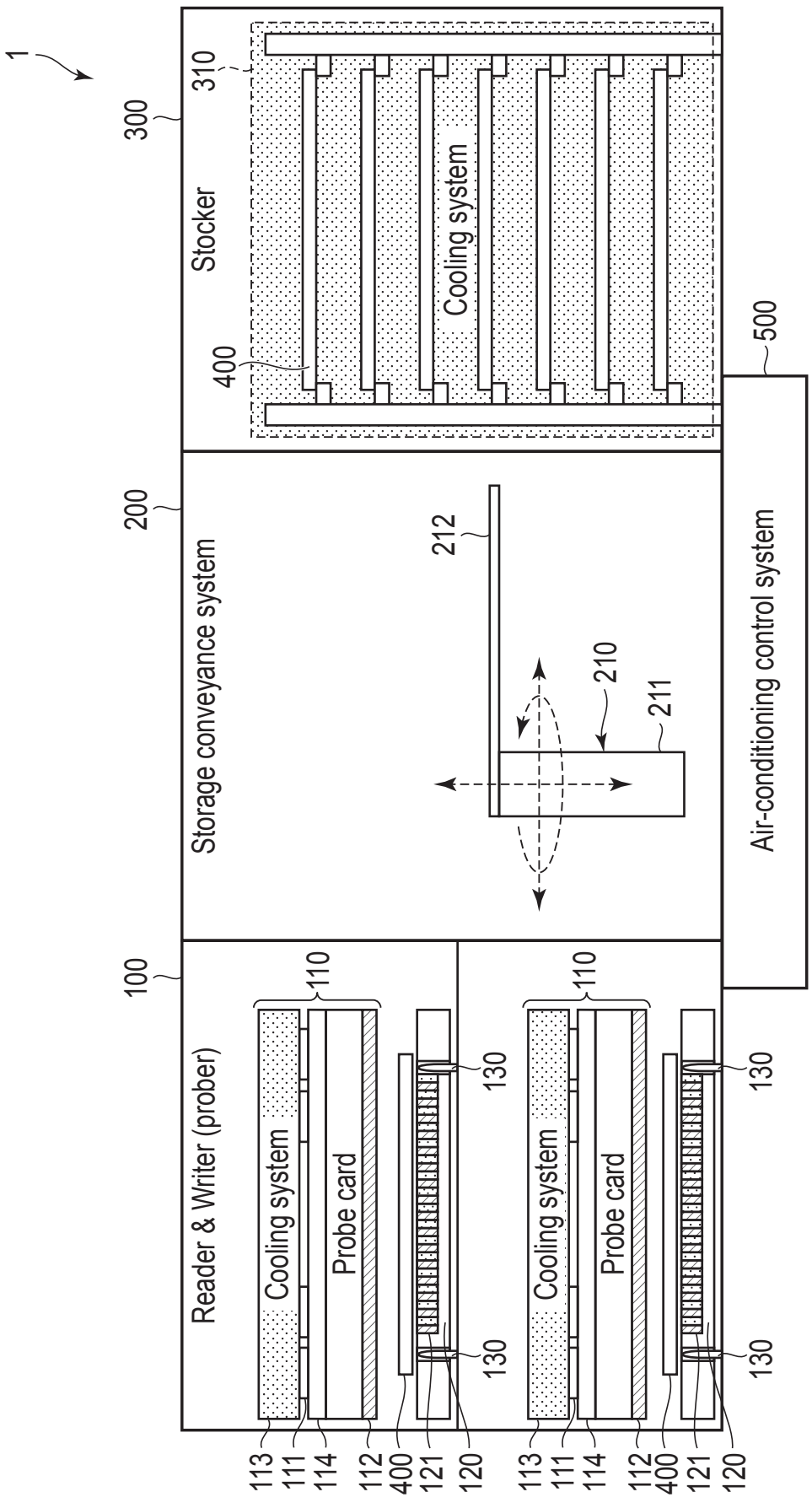

1
300
Stocker
310
Cooling system
400
500
200
Storage conveyance system
212
210
211
Air-conditioning control system
100
Reader & Writer (prober)
110
Cooling system
Probe card
130
113
111
114
112
400
121
120

FIG. 1

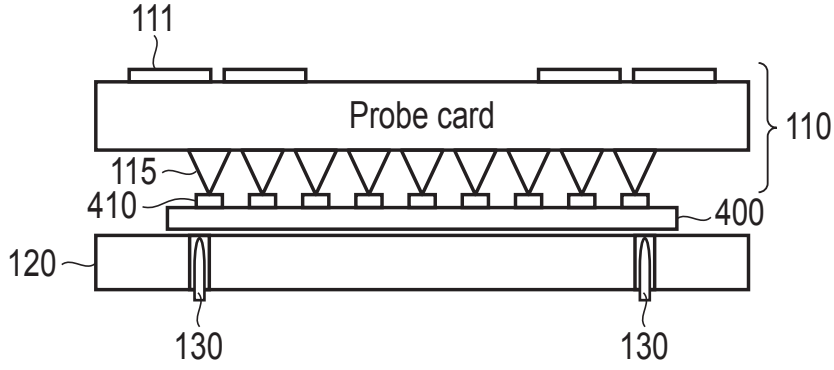

111
Probe card
110
115
410
400
120
130
130

FIG. 2

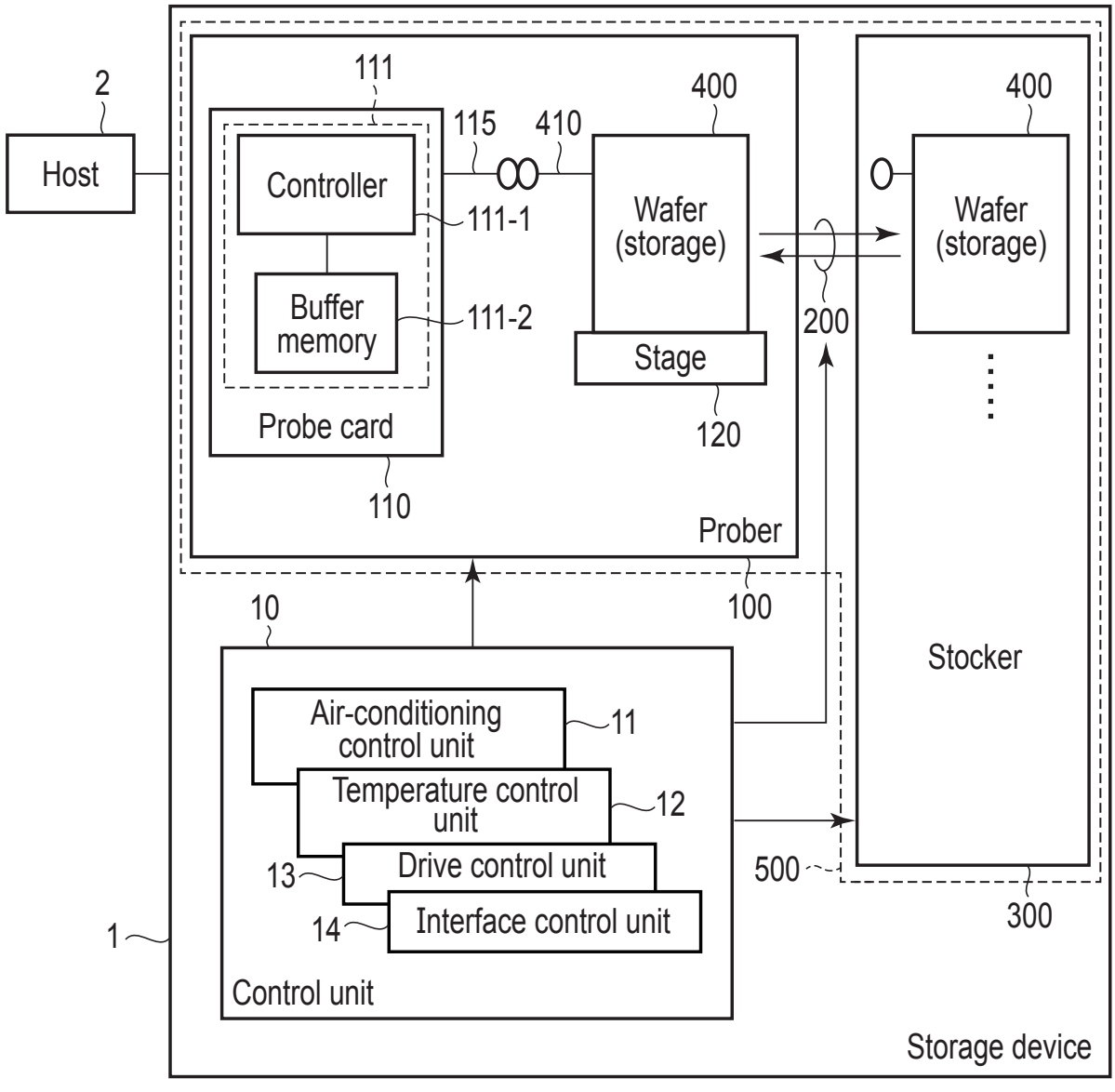

2
Host
111
Controller
111-1
Buffer memory
111-2
Probe card
110
115
410
400
Wafer (storage)
Stage
120
Prober
100
200
400
Wafer (storage)
Stocker
300
500
10
Air-conditioning control unit
11
Temperature control unit
12
13
Drive control unit
14
Interface control unit
Control unit
1
Storage device

FIG. 3

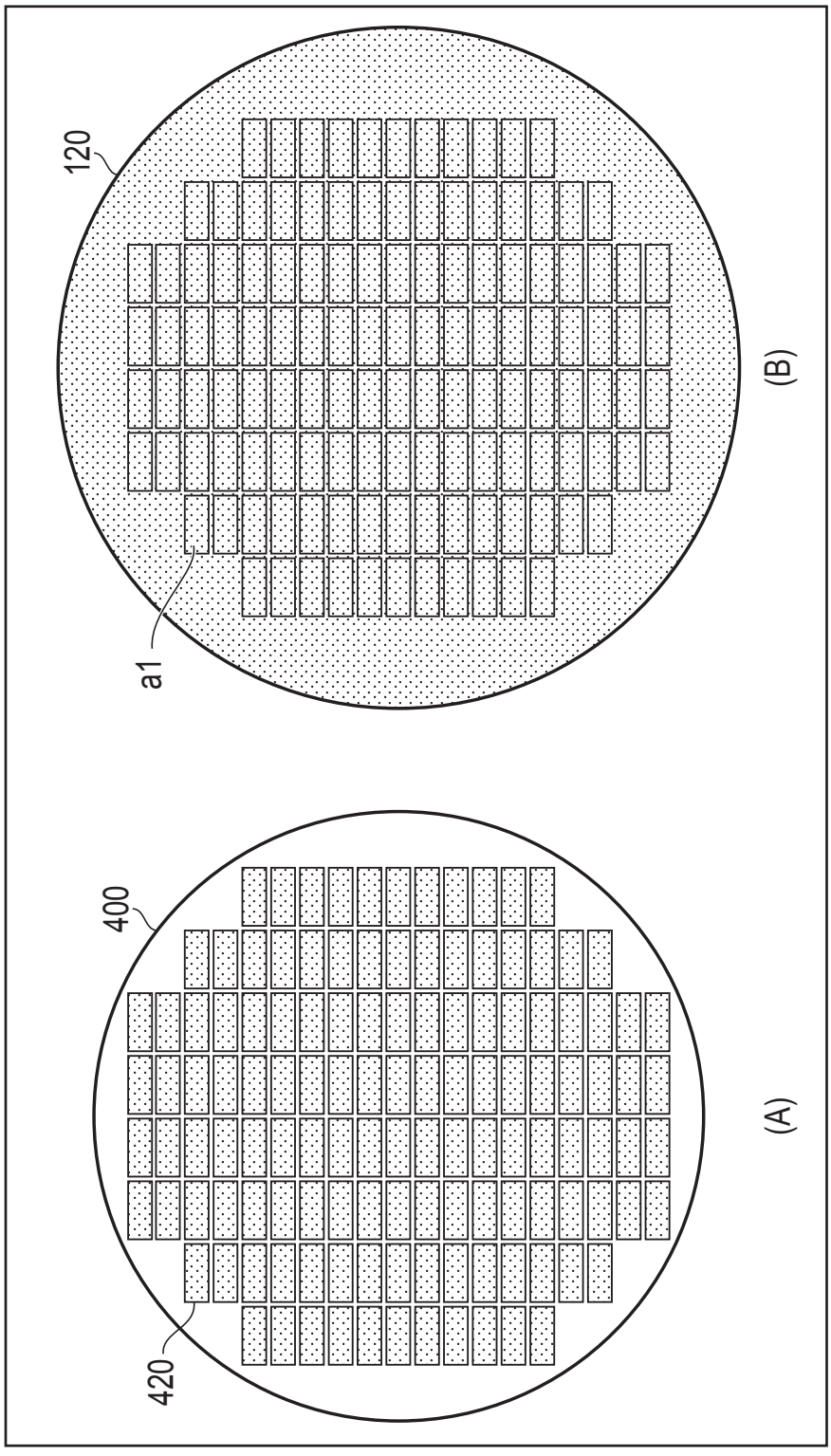


FIG. 4

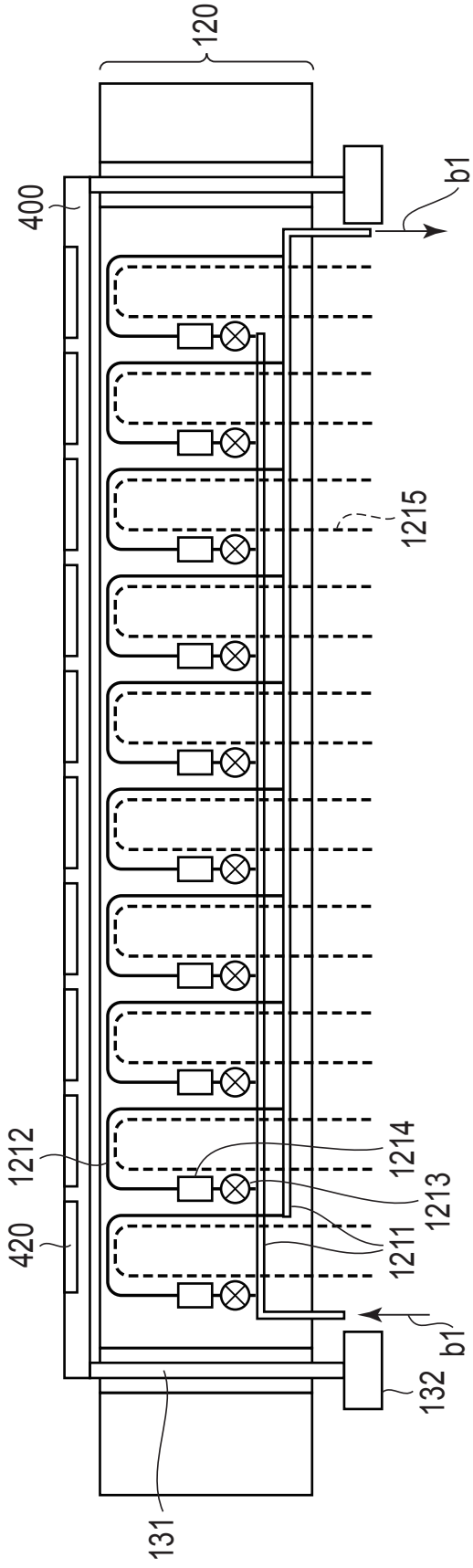


FIG. 5

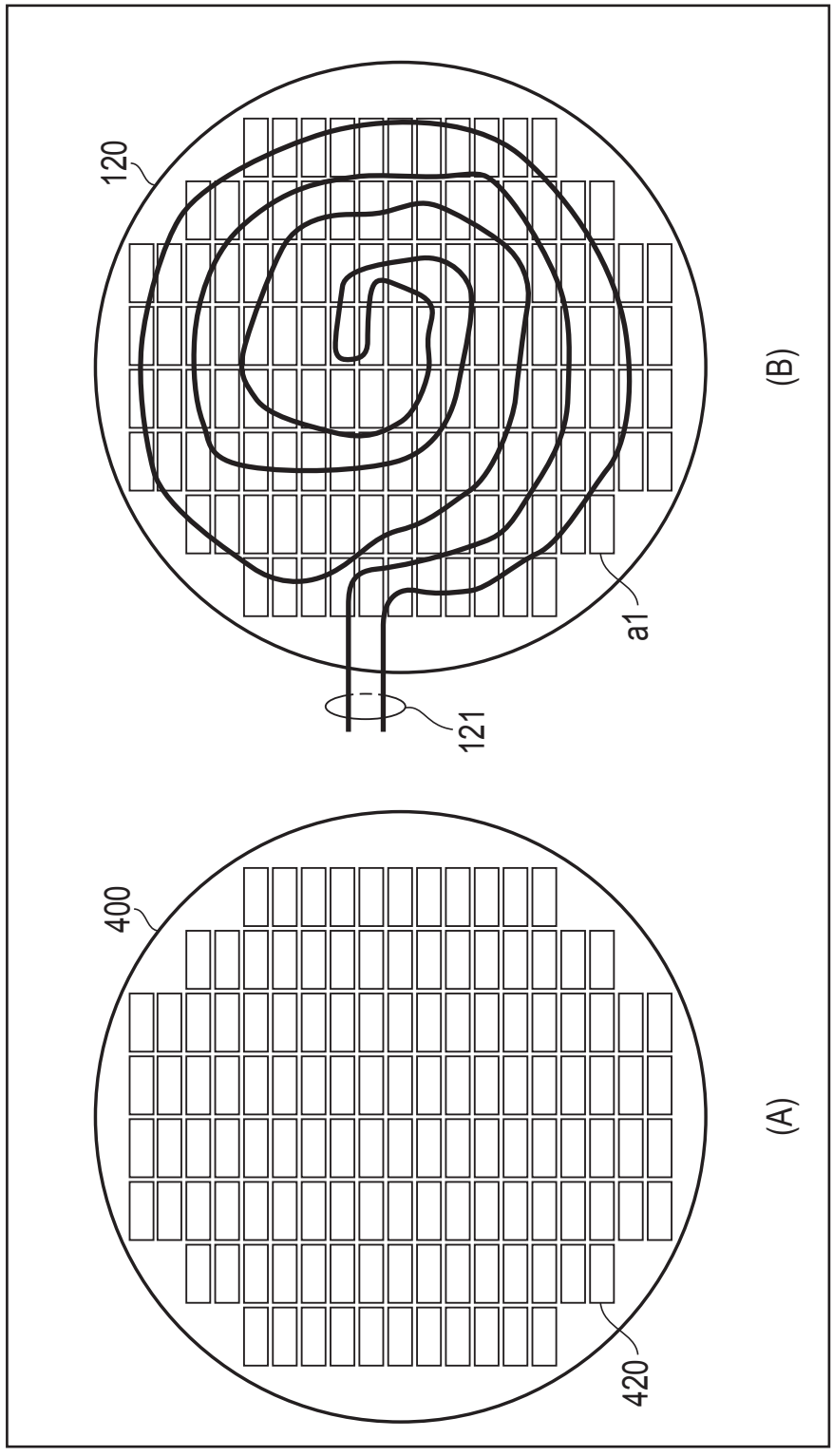


FIG. 6

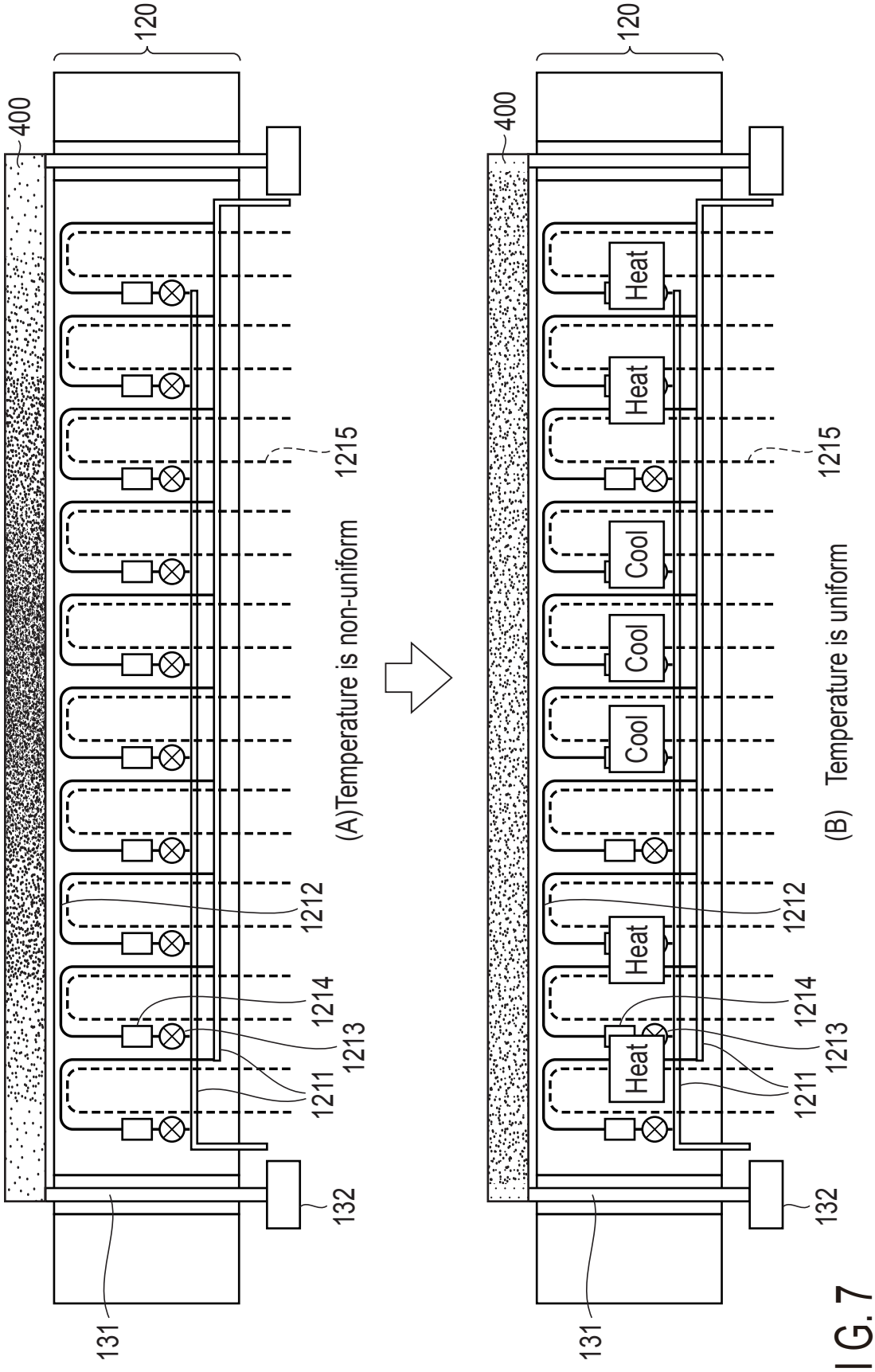

120
400
1215
(A)Temperature is non-uniform
1212
1214
1213
1211
132
131
120
400
Heat
Heat
Cool
Cool
Cool
Heat
Heat
1215
(B) Temperature is uniform
1212
1214
1213
1211
132
131

FIG. 7

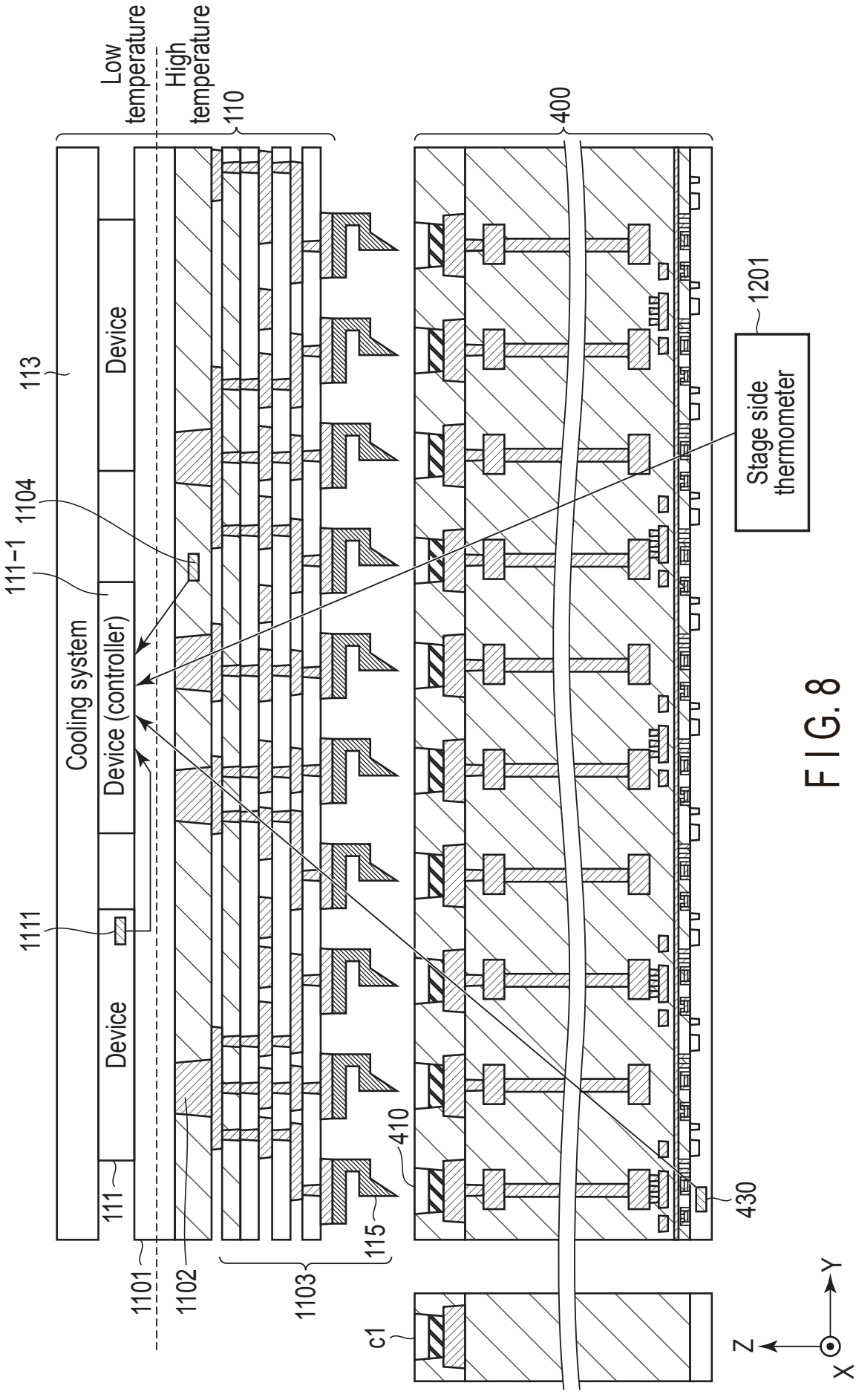

Low temperature
High temperature
110
400
113
Device
Device (controller)
Cooling system
Device
Device
111-1
1104
1111
111
1101
1102
1103
115
410
c1
430
1201
Stage side thermometer
Z
Y
X

FIG. 8

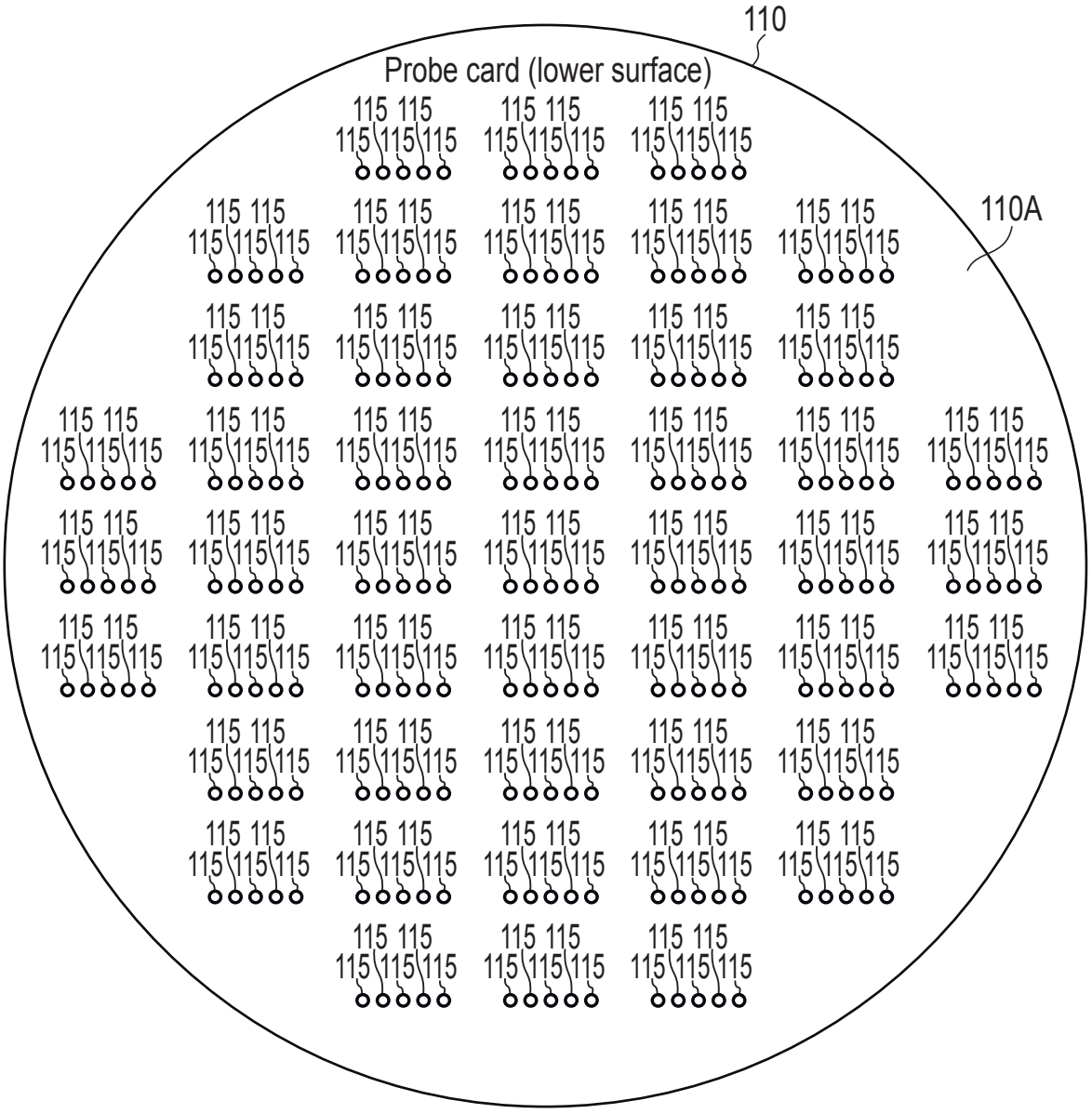


FIG. 9

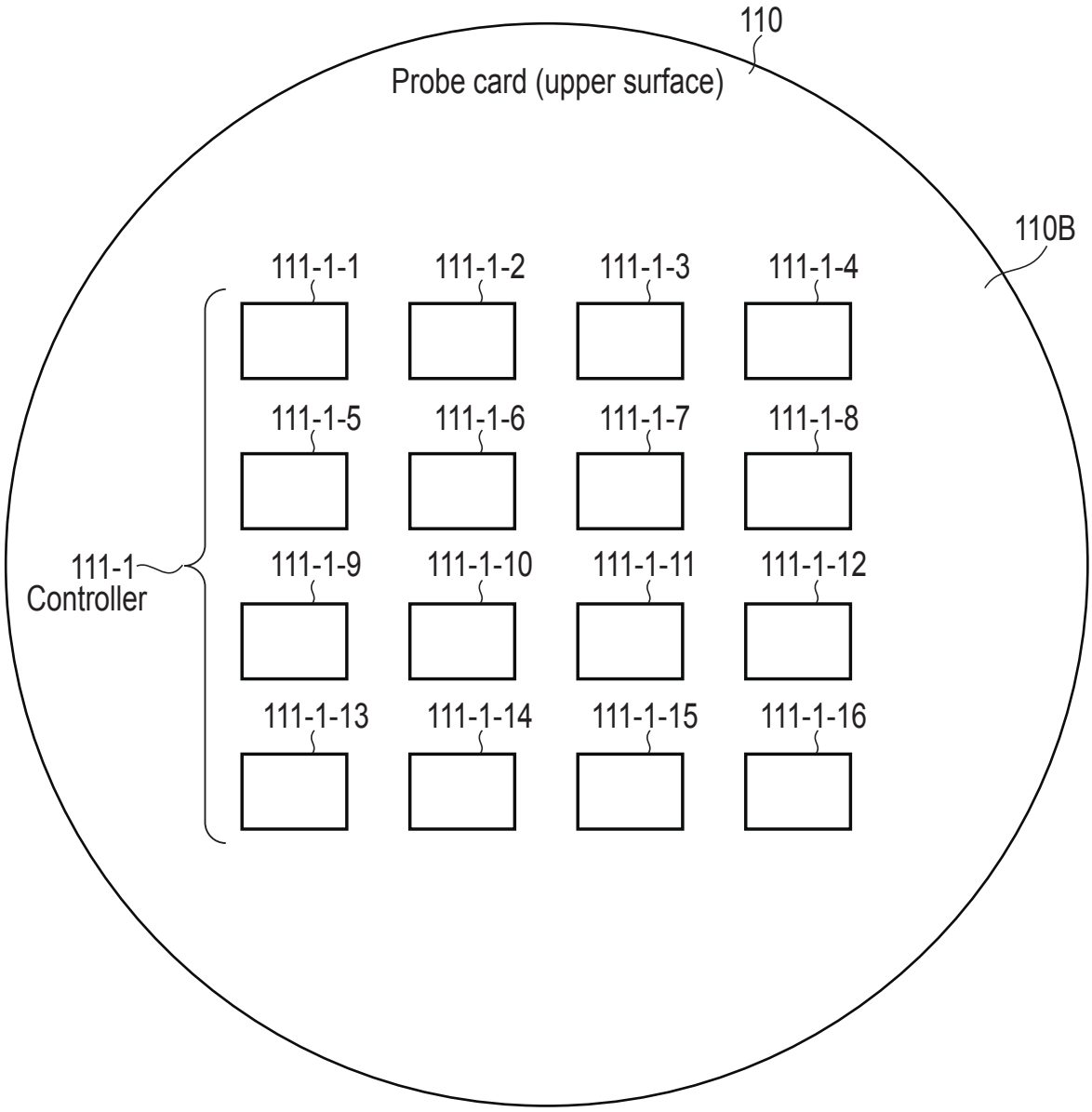

110
Probe card (upper surface)
110B
111-1-1
111-1-2
111-1-3
111-1-4
111-1-5
111-1-6
111-1-7
111-1-8
111-1
Controller
111-1-9
111-1-10
111-1-11
111-1-12
111-1-13
111-1-14
111-1-15
111-1-16

FIG. 10

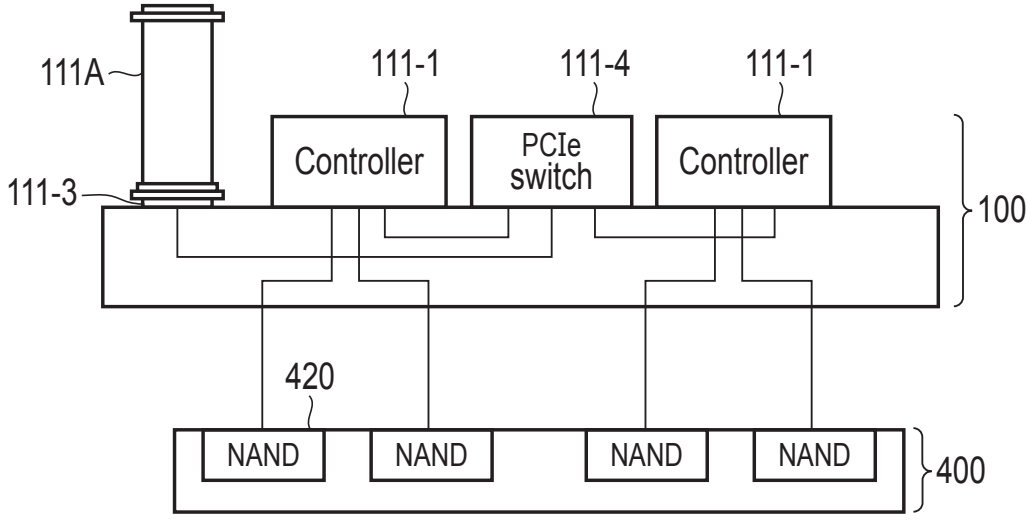

111A
111-1
111-4
111-1
Controller
PCIe
switch
Controller
111-3
100
420
NAND
NAND
NAND
NAND
400

FIG. 11

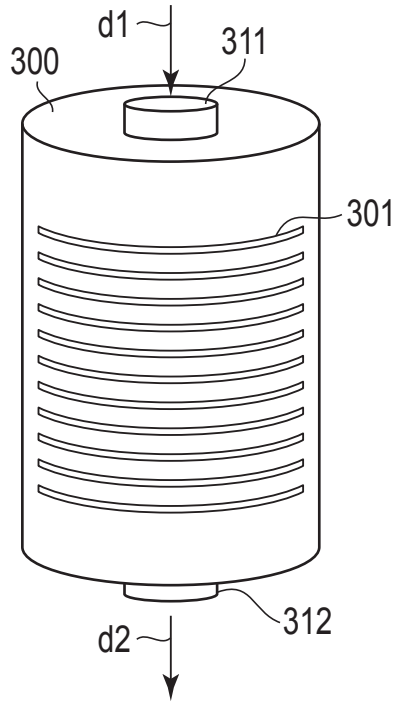


FIG. 12

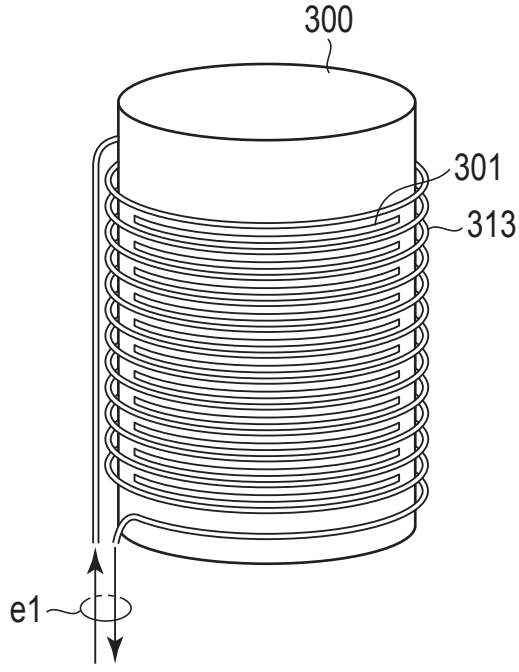


FIG. 13

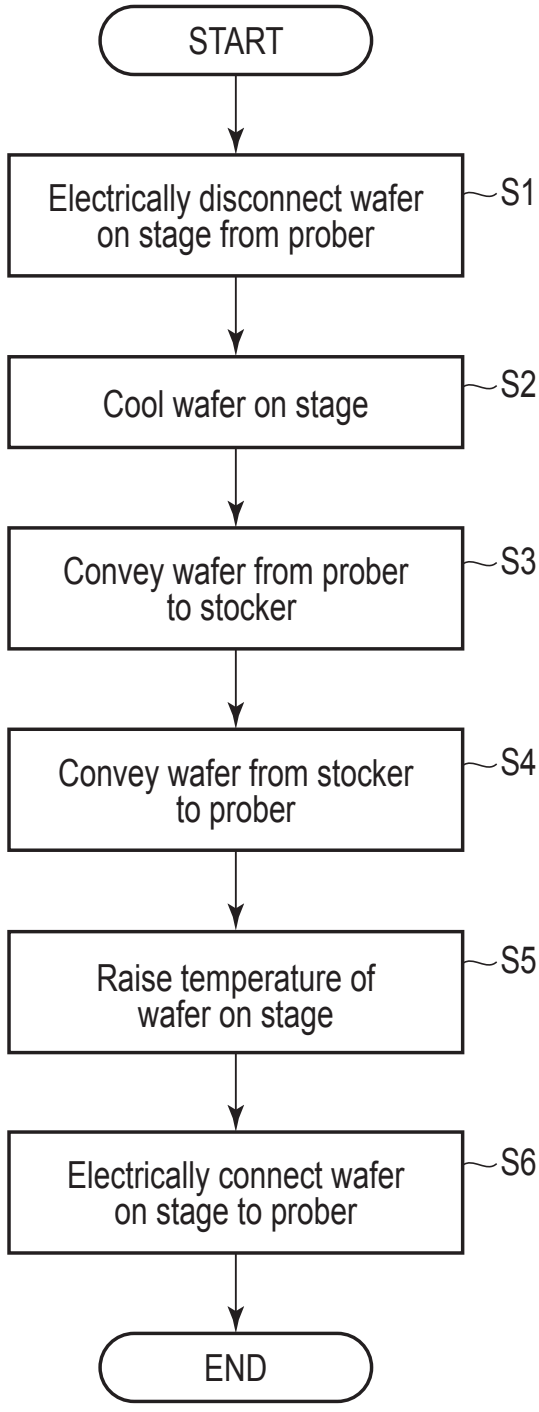

START
Electrically disconnect wafer on stage from prober
S1
Cool wafer on stage
S2
Convey wafer from prober to stocker
S3
Convey wafer from stocker to prober
S4
Raise temperature of wafer on stage
S5
Electrically connect wafer on stage to prober
S6
END

FIG. 14